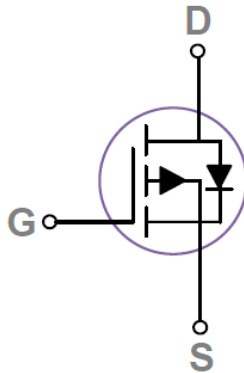
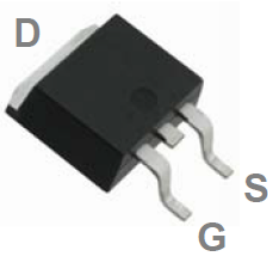


## General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

## TO252 Pin Configuration



BVDSS	RDSON	ID
-30V	4.5mΩ	-85A

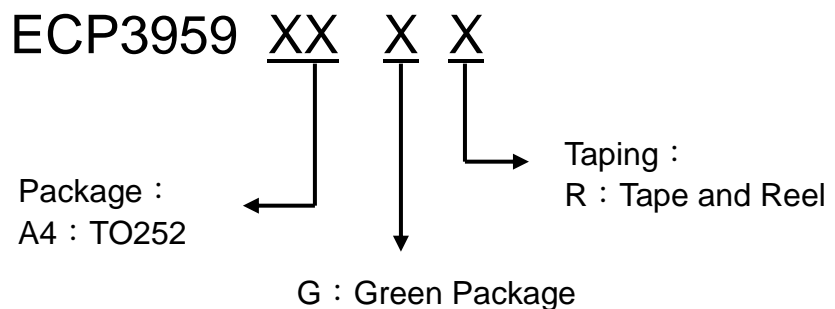
## Features

- ◆ -30V, -85A, RDS(ON) = 4.5mΩ @ VGS = -10V
- ◆ Fast switching
- ◆ Green Device Available
- ◆ Suit for -4.5V Gate Drive Applications

## Application

- ◆ Motor Driver Applications
- ◆ POL Applications
- ◆ Load Switch
- ◆ LED Application

## Ordering Information



**Absolute Maximum Ratings**  $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_C=25^\circ\text{C}$ )	-85	A
	Drain Current – Continuous ( $T_C=100^\circ\text{C}$ )	-54	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	-340	A
$P_D$	Power Dissipation ( $T_C=25^\circ\text{C}$ )	104	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.83	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.2	$^\circ\text{C}/\text{W}$

**Electrical Characteristics**  $T_J=25^\circ\text{C}$ , unless otherwise noted**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.03	---	V/ $^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-30\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{DS}=-24\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$ , $I_D=-30\text{A}$	---	3.5	4.5	m
		$V_{GS}=-4.5\text{V}$ , $I_D=-20\text{A}$	---	5	7	m
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu\text{A}$	-1.2	-1.6	-2.2	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	4	---	mV/ $^\circ\text{C}$
gfs	Forward Transconductance	$V_{DS}=-10\text{V}$ , $I_D=-5\text{A}$	---	25	---	S

### Dynamic and switching Characteristics

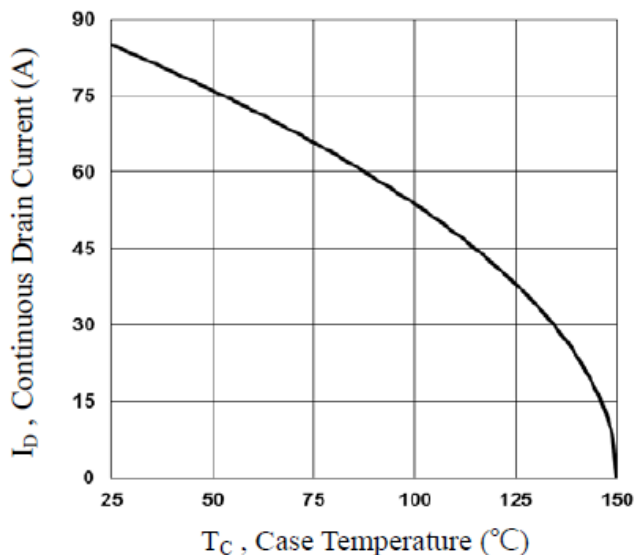
Qg	Total Gate Charge <sup>2, 3</sup>	$V_{DS}=-15V, V_{GS}=-10V, I_D=-10A$	---	108	150	nC
Qgs	Gate-Source Charge <sup>2, 3</sup>		---	15	25	
Qgd	Gate-Drain Charge <sup>2, 3</sup>		---	17.4	30	
Td(on)	Turn-On Delay Time <sup>2, 3</sup>	$V_{DD}=-15V, V_{GS}=-10V, R_G=6\Omega, I_D=-1A$	---	28	56	ns
Tr	Rise Time <sup>2, 3</sup>		---	16	32	
Td(off)	Turn-Off Delay Time <sup>2, 3</sup>		---	178	340	
Tf	Fall Time <sup>2, 3</sup>		---	72	140	
Ciss	Input Capacitance	$V_{DS}=-25V, V_{GS}=0V, F=1MHz$	---	6220	9000	pF
Coss	Output Capacitance		---	782	1100	
Crss	Reverse Transfer Capacitance		---	412	600	

### Drain-Source Diode Characteristics and Maximum Ratings

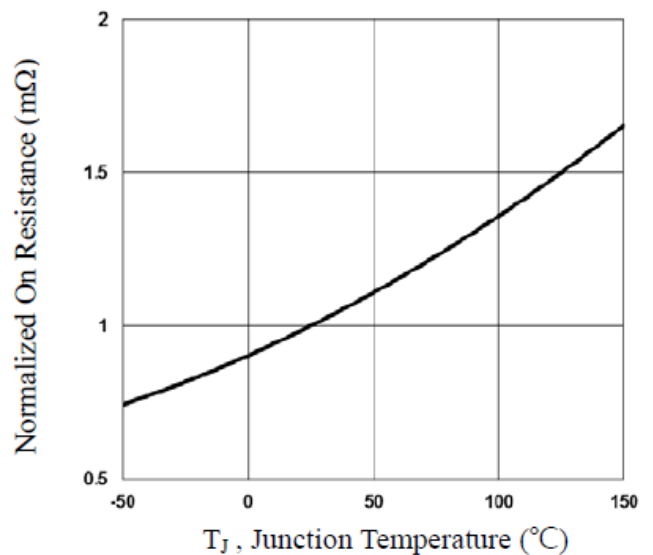
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V, \text{ Force Current}$	---	---	-85	A
$I_{SM}$	Pulsed Source Current		---	---	-170	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=-1A, T_J=25^\circ C$	---	---	-1	V

Note :

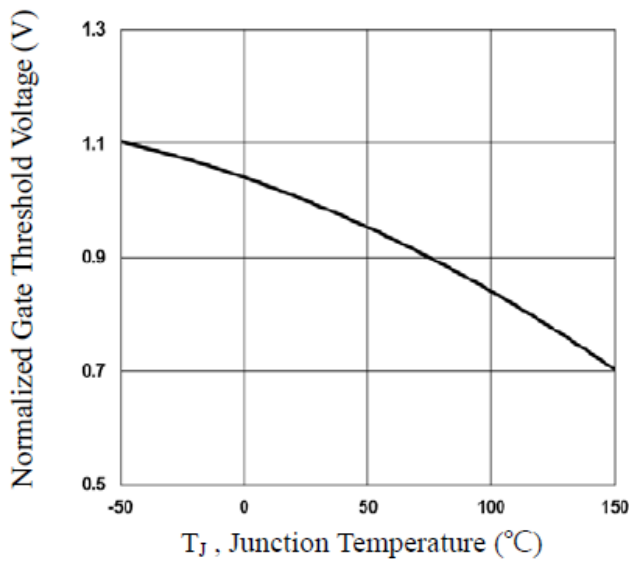
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.



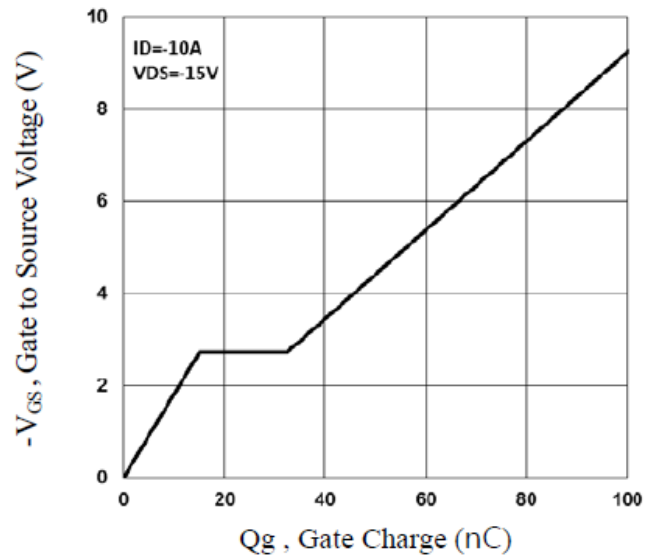
**Fig.1 Continuous Drain Current vs.  $T_C$**



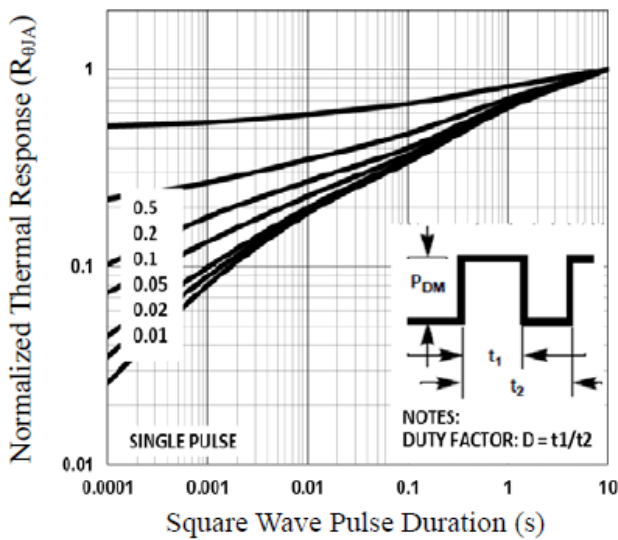
**Fig.2 Normalized RDSON vs.  $T_J$**



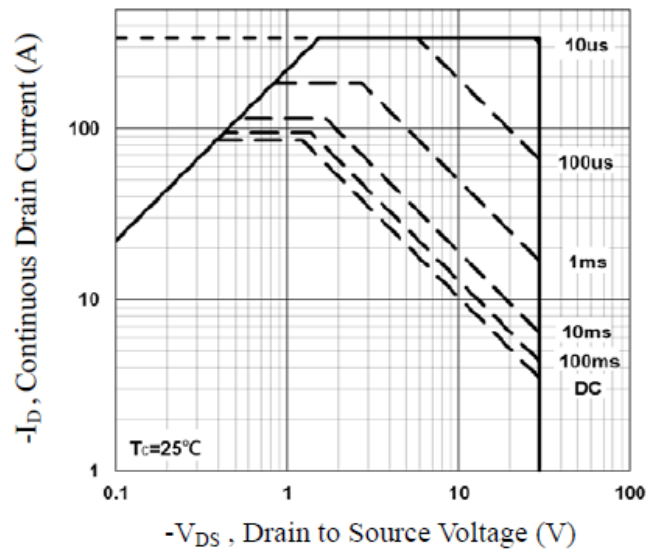
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



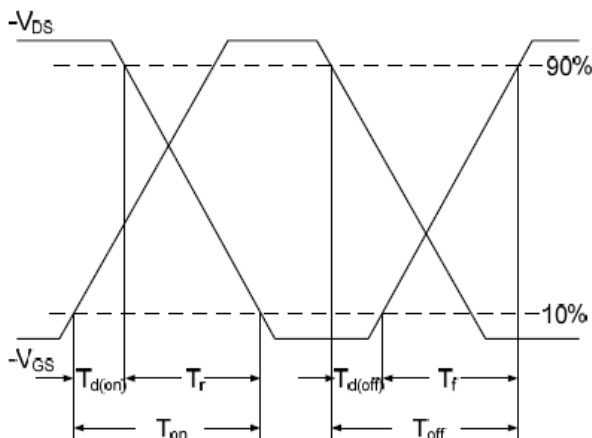
**Fig.4 Gate Charge Waveform**



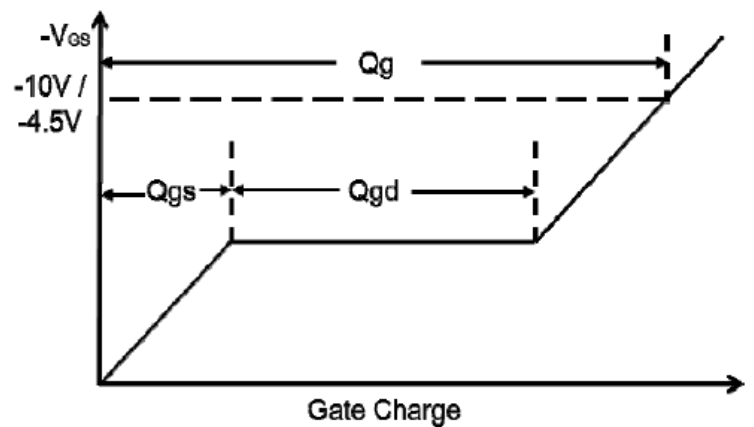
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

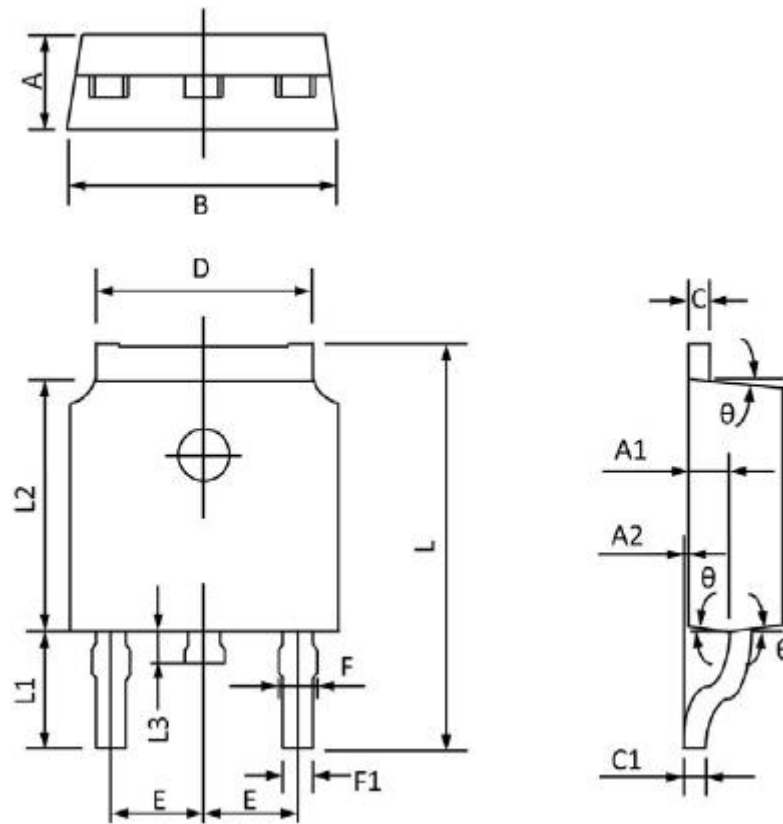


**Fig.7 Switching Time Waveform**



**Fig.8 Gate Charge Waveform**

TO252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°